

Customer No.: 31561
Application No.: 10/063,976
Docket No.: 7287-US-PA

REMARKS

Present Status of the Application

Claim 1-13 are allowed. The Office Action rejected presently pending claims 14-20. Specifically, the Office Action rejected claims 14-20 under 35 U.S.C. 103(a), as being unpatentable over Onitsuka et al. (U. S. Patent 6,049,167) in view of Vinouze et al. (U.S. Patent 5,326,420). Claims 8-14 remain pending in the present application, and reconsideration of those claims is respectfully requested.

Discussion of Office Action Rejections

The Office Action rejected claims 14-20 under 35 U.S.C. 103(a), as being unpatentable over Onitsuka et al. in view of Vinouze et al. Applicants respectfully traverse the rejections for at least the reasons set forth below.

In Applicants' invention, a trench is formed at an edge of a lamination plate to prevent overflow of the sealing agent after a subsequent lamination process, and control the dimension of the UV or thermal curing resin. Therefore, the adhesion between the UV or thermal curing resin, the lamination plate, and the substrate will be improved by the global coating effect as mentioned on lines 2-3, para.22 and in the summary of the invention, para.8. Independent claim 14 recites the features as follows:

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14. A package apparatus for an organic electro-luminescent display, comprising at least:

a panel supply system, to provide a panel comprising an organic electro-luminescent display thereon;

a sealing agent coating system, to interpose a certain amount of a sealing agent between the panel and a lamination plate;

a lamination plate supply system, to provide the lamination plate which further comprises a trench formed at a periphery thereon;

an alignment and lamination system, to align and laminate the lamination plate and the panel; and

a curing system, to cure the sealing agent.

(Emphasis added).

However, both Onitsuka and Vinouze were never before recognized the problem and mean solved by present invention. Although Vinouze teaches the lamination plate having a groove on lines 46-49 of col.2, the groove is used as a suction device for holding substrates instead of controlling the width of sealant by forming a gap in present invention. "The claimed invention must be considered as a whole, and the question is whether there is something in the prior art as a whole to suggest the desirability, and thus the obviousness, of making the combination." *Maschinenfabrik GMBH v. American Hoist & Derrick*, 221 U.S.P.Q.481, 488 (Fed.Cir.1984). The recognition of an unrecognized problem militates in favor of patentability.

On the other hand, the lamination plate disclosed on lines 6-13 of col.5 of Onitsukas' invention consisted of a rectangular top member (D21) and a side wall (D22) as illustrated in figure 1. However, the lamination plate in present invention is a flat plate of glass without side

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walls and includes a groove formed at an edge thereof to prevent overflow of the sealant after a subsequent lamination process. A side wall element of the prior-art device has been omitted without loss of capability. It militates non-obvious.

As described previously, Onitsuka and Vinouze failed to disclose the features of "a lamination plate supply system, to provide the lamination plate which further comprises a trench formed at a periphery thereon" as recited in independent claim 14. Meanwhile, if the combination of Onitsuka and Vinouze is made, the references would produce an inoperative combination..

For at least the foregoing reasons, Applicants respectfully submit that independent claim 14 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 15-20 patently define over the prior art as well.

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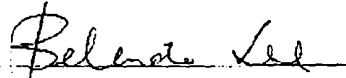
CONCLUSION

The abovementioned facts fully support the patentability of the pending claims 14-20. Accordingly, it is most respectfully requested that this rejection be withdrawn. The Examiner is invited to call the undersigned to facilitate the advancement of the above-identified patent application.

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Respectfully submitted,



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